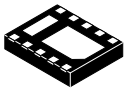


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

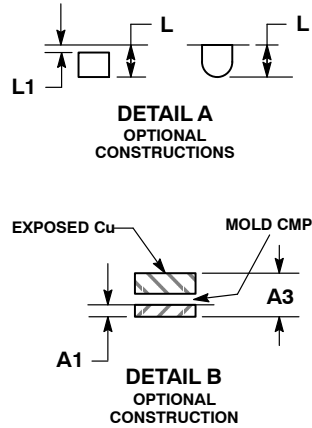
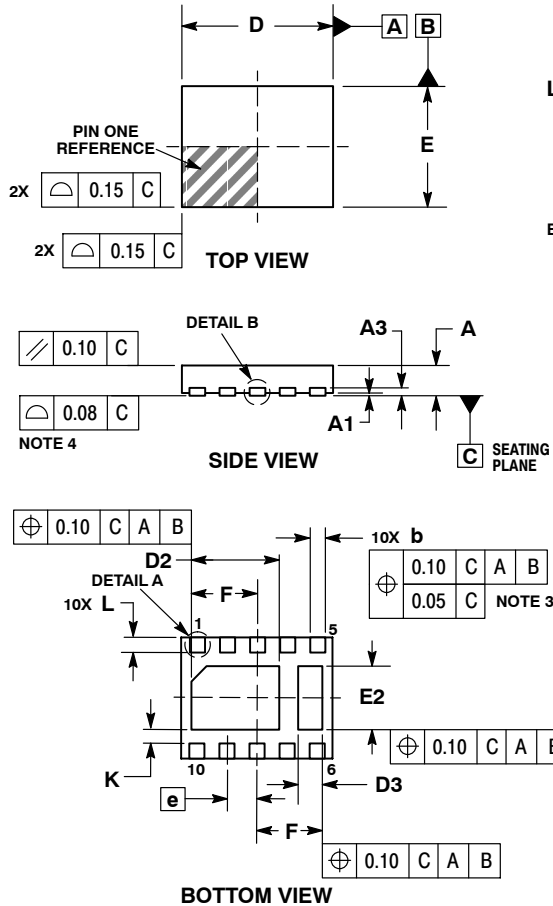
ON Semiconductor®



SCALE 4:1

UDFN10 2.5x2, 0.5P  
CASE 517AV-01  
ISSUE A

DATE 12 FEB 2009

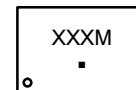


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.45        | 0.55 |
| A1  | 0.00        | 0.05 |
| A3  | 0.13 REF    |      |
| b   | 0.20        | 0.30 |
| D   | 2.50 BSC    |      |
| D2  | 1.35        | 1.55 |
| D3  | 0.30        | 0.50 |
| E   | 2.00 BSC    |      |
| E2  | 0.95        | 1.15 |
| e   | 0.50 BSC    |      |
| F   | 1.08 BSC    |      |
| K   | 0.20        | ---  |
| L   | 0.20        | 0.30 |
| L1  | ---         | 0.15 |

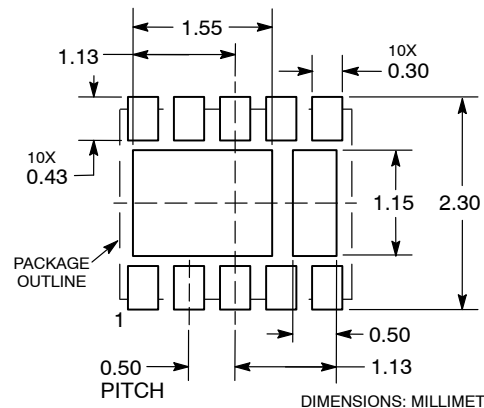
**GENERIC  
MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                           |  |
|-------------------------|---------------------------|--|
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| <b>STATUS:</b>          | ON SEMICONDUCTOR STANDARD |  |
| <b>NEW STANDARD:</b>    |                           |  |
| <b>DESCRIPTION:</b>     | UDFN10 2.5X2, 0.5P        | <b>PAGE 1 OF 2</b>   |



| ISSUE | REVISION                                       | DATE        |
|-------|--|-------------|
| O     | RELEASED FOR PRODUCTION. REQ. BY C. GIOIA.     | 12 NOV 2008 |
| A     | REVISED SOLDERING FOOTPRINT. REQ. BY C. GIOIA. | 12 FEB 2009 |
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